

## **LISTING OF CLAIMS**

1. (Previously Presented) A polishing pad comprising:  
a polishing body comprising a material wherein said material is a cross-linked polymer having a hardness ranging from about 34 Shore A to about 60 Shore A.
2. (Original) The polishing pad as recited in Claim 1 wherein said cross-linked polymer is a thermoplastic foam.
3. (Original) The polishing pad as recited in Claim 1 wherein said cross-linked polymer has a closed cell structure.
4. (Original) The polishing pad as recited in Claim 3 wherein said cross-linked polymer is polyethylene.
5. (Original) The polishing pad as recited in Claim 1 wherein said polishing body includes a base pad and said cross-linked polymer forms a polishing surface located over said base pad.
6. (Original) The polishing pad as recited in Claim 1 wherein said cross-linked polymer is a polyethylene having a closed cell structure.

Claim 7 (Canceled)

8. (Original) The polishing pad as recited in Claim 1 wherein said cross-linked polymer has a selectivity of Cu to Ta removal rates of greater than about 27:1.

Claims 9-27 (Canceled).

28. (New) The polishing pad as recited in Claim 1 wherein said hardness is about 34 Shore A.